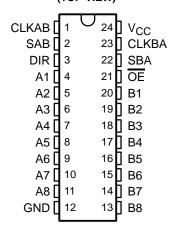
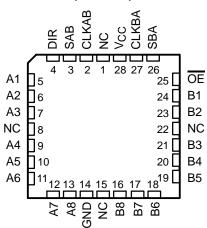
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 11 ns

SN54HC646 ... JT OR W PACKAGE SN74HC646 ... DW OR NT PACKAGE (TOP VIEW)



- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths

SN54HC646 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### description/ordering information

The 'HC646 devices consist of bus-transceiver circuits with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'HC646 devices.

Output-enable ( $\overline{OE}$ ) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either or both registers.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when  $\overline{OE}$  is active (low). In the isolation mode ( $\overline{OE}$  high), A data may be stored in one register and/or B data may be stored in the other register.

#### ORDERING INFORMATION

TA	SOIC – DW	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT	Tube	SN74HC646NT	SN74HC646NT
–40°C to 85°C	SOIC DW		HC646	
	SOIC - DW	Tape and reel	SN74HC646DWR	ПС040
	CDIP – JT	Tube	SNJ54HC646JT	SNJ54HC646JT
–55°C to 125°C	CFP – W	Tube	SNJ54HC646W	SNJ54HC646W
	LCCC – FK	Tube	SNJ54HC646FK	SNJ54HC646FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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## description/ordering information (continued)

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

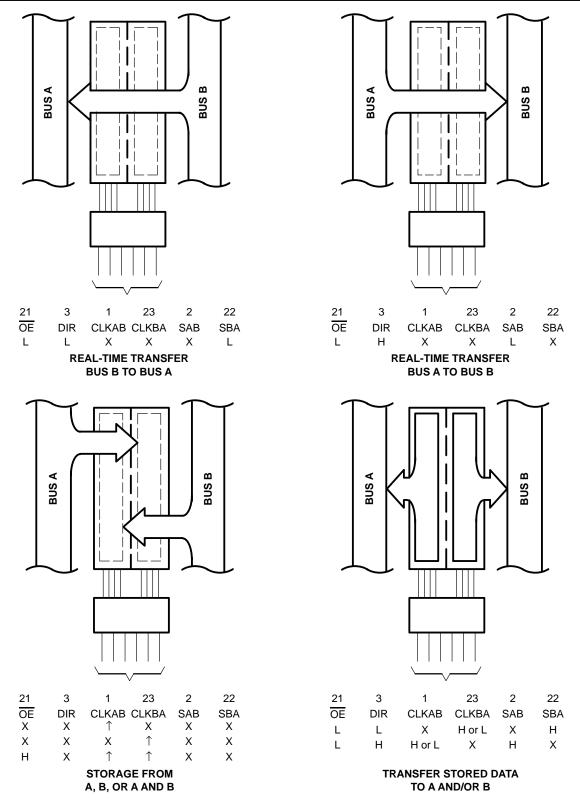
When an output function is disabled, the input function is still enabled and can be used to store data. Only one of the two buses, A or B, may be driven at a time.

#### **FUNCTION TABLE**

		INP	UTS			DAT	A I/O	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified <sup>†</sup>	Store A, B unspecified <sup>†</sup>
Х	X	Χ	$\uparrow$	X	Χ	Unspecified <sup>†</sup> Input		Store B, A unspecified <sup>†</sup>
Н	Х	1	<b>↑</b>	Х	Х	Input	Input	Store A and B data
Н	Χ	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Х	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Х	Н	Χ	Input	Output	Stored A data to B bus

The data-output functions can be enabled or disabled by various signals at  $\overline{\text{OE}}$  and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



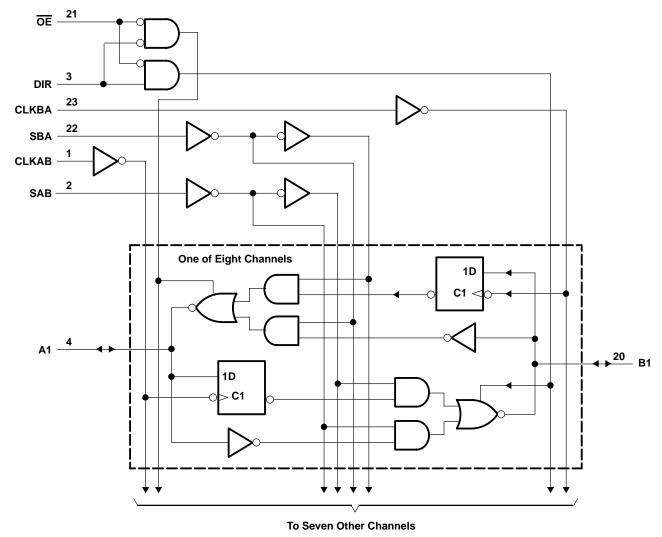


Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions



### logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, $V_{CC}$	
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	
Continuous current through V <sub>CC</sub> or GND	±70 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DW package	46°C/W
(see Note 3): NT package	67°C/W
Storage temperature range, T <sub>stg</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-3.



## recommended operating conditions (see Note 4)

			SN	154HC64	<b>16</b>	SN	174HC64	ŀ6	LINIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
ViH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		V <sub>CC</sub> = 6 V	4.2		7	4.2			
		V <sub>CC</sub> = 2 V		Ą	0.5			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$		Q'	1.35			1.35	V
		V <sub>CC</sub> = 6 V		5	1.8			1.8	
٧ı	Input voltage		0	5	VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V	Q		1000			1000	
t <sub>t</sub>	Input transition (rise and fall) time	$V_{CC} = 4.5 V$			500			500	ns
		V <sub>CC</sub> = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETED	TEST OF	NUNTIONS	V	Т	A = 25°C	;	SN54F	IC646	SN74H	IC646	LINUT
PAR	AMETER	lesi co	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
				2 V	1.9	1.998		1.9		1.9		
			$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Vон		VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7	7	3.84		V V nA μA μA
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	1/5/	5.34		
				2 V		0.002	0.1		0.1		0.1	
			$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL		$V_I = V_{IH}$ or $V_{IL}$		6 V		0.001	0.1	3	0.1		0.1	0.1 V
			$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26	90	0.4		0.33	
			$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26	y <sub>d</sub>	0.4		0.33	
lį	Control inputs	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	A or B	VO = VCC  or  0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc		$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci	Control inputs			2 V to 6 V		3	10		10		10	pF

## SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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## timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V	T <sub>A</sub> =	25°C	SN54H	C646	SN74H	IC646	LINUT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		6		4.3		5.5	
fclock	Clock frequency	4.5 V		31		22		27	MHz
		6 V		36     25     31       0     115     95       6     23     19					
		2 V	80		115	151	95		
$t_{W}$	Pulse duration, CLKBA or CLKAB high or low	4.5 V	16		23	EL	19		ns
		6 V	14		20	2	16		
			100		150	,	125		
t <sub>su</sub>	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5 V	20		30		25		ns
		6 V	17		26		21		
		2 V	5		5		5		
th	Hold time, A after CLKAB↑ or B after CLKBA↑	4.5 V	5		5		MAX         MIN         MAX           4.3         5.5           22         27           25         31           95         19           16         125           25         21           5         5	ns	
		6 V	5		5		5		



# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

DADAMETER	FROM	то	V	T,	Δ = 25°C	;	SN54H	IC646	SN74H	C646	UNIT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V	6	11		4.4		5.5		
f <sub>max</sub>			4.5 V	31	54		22		27		MHz
			6 V	36	64		25		31		
			2 V		65	180		270		225	
	CLKBA or CLKAB	A or B	4.5 V		18	36		54		45	
			6 V		14	31		46		38	
			2 V		50	135		205		170	
t <sub>pd</sub>	A or B	B or A	4.5 V		14	27		41		34	ns
			6 V		11	23		35		29	
			2 V		70	190		285		240	
	SBA or SAB†	A or B	4.5 V		20	38		57		48	
			6 V		16	32		48		41	
			2 V		85	245	7	370		305	
t <sub>en</sub>	ŌĒ	A or B	4.5 V		25	49	032	74		61	ns
			6 V		20	42	70	63		52	
			2 V		85	245	d	370		305	
t <sub>dis</sub>	ŌĒ	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		80	245		370		305	
<sup>t</sup> en	DIR	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		80	245		370		305	
<sup>t</sup> dis	DIR	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		28	60		90		75	
t <sub>t</sub>		Any	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

## SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCLS150C - DECEMBER 1982 - REVISED MARCH 2003

## switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 2)

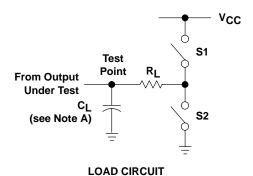
PARAMETER	FROM	то	V	T,	λ = 25°C	;	SN54H	C646	SN74H	C646	UNIT								
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII								
			2 V		90	265		400		330									
	CLKBA or CLKAB	A or B	4.5 V		24	53		80		66									
			6 V		20	46		68		57									
			2 V		70	220		335		280									
<sup>t</sup> pd	A or B	B or A	4.5 V		20	44		67		56	ns								
			6 V		15	38		57		49									
			2 V		80	275		415		345									
	SBA or SAB†	A or B	4.5 V		24	55	~~/												
			6 V		20	47	C)	70		60									
			2 V		113	330	20	500		410									
	ŌĒ	A or B	4.5 V		33	66	) V	100		82									
			6 V		27	57	/	85		71	ns								
t <sub>en</sub>			2 V		113	330		500		410	115								
	DIR	A or B	4.5 V		33	66		100		82									
			6 V		27	57		85		71									
			2 V		45	210		315		265									
t <sub>t</sub>		Any	Any	Any	Any	Any	Any	Any	Any	Any	4.5 V		17	42		63		53	ns
			6 V		13	36		53		43									

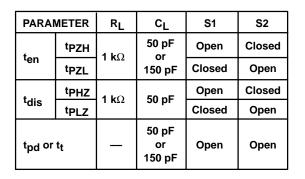
<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

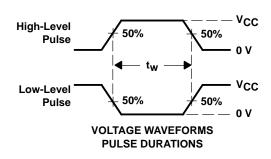
## operating characteristics, $T_A = 25^{\circ}C$

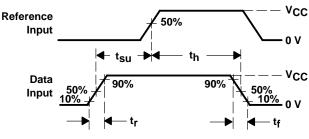
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	50	pF

#### PARAMETER MEASUREMENT INFORMATION

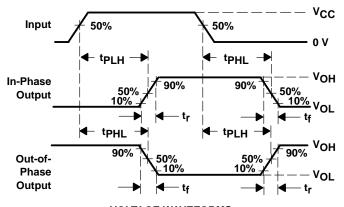


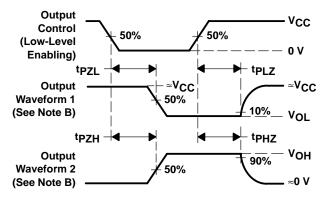






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 6$  ns.
- D. For clock inputs, f<sub>max</sub> is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms







com 18-Sep-2008

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74HC646DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC646DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC646DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC646DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC646DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC646DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC646NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC646NT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74HC646NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

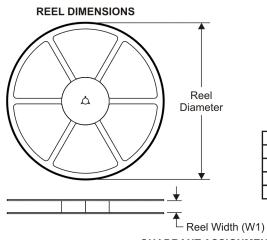
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

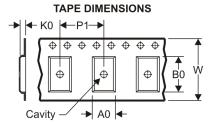
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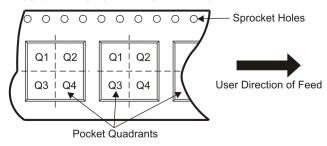
### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

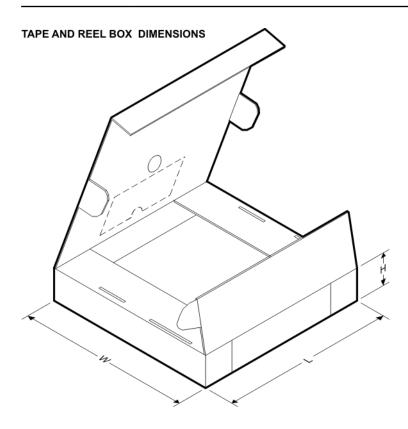
## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC646DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1





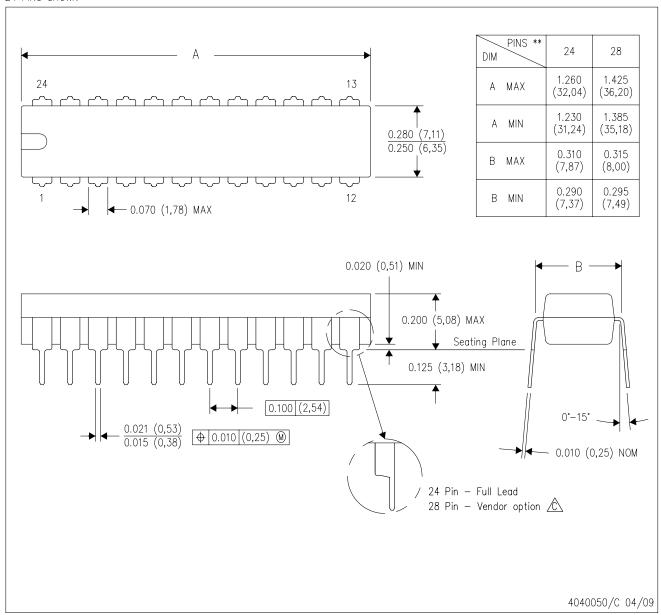
#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC646DWR	SOIC	DW	24	2000	346.0	346.0	41.0

## NT (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

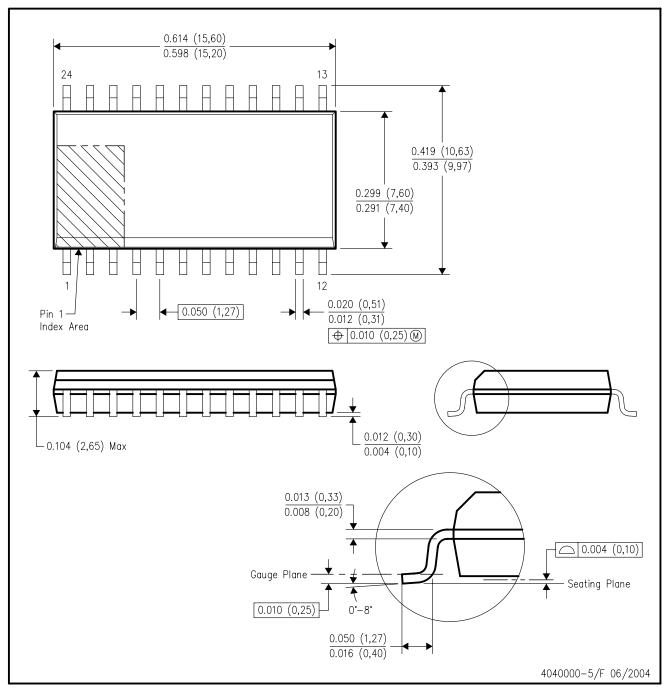
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



## DW (R-PDSO-G24)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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